IBS
Innovative ion implant
Company at a glance

• France, Scotland, Singapour, US
• > 80 employees
  • 25 in R&I
• 15 M€
• R&I expenses representing 18% of sales
• Ion implantation equipments and processes, surface engineering for advanced nano-electronics and specialties (power, compound semi-conductors, imagers, sensors …)
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IBS PRODUCTS

> **PULSION :** for advanced nano-electronic
  > Logic and memories
  > Servers, PC, smartphones ...

> **IMC / FLEXion :** for R&D and production
  > Specialties components
  > Telecom, Power, IoT (capteurs) ...

> **AMAT series full refurb**
  > Proton separation process
  > Power, IOT 200 mm fabs

> **PULSION SOLAR :**
  > High performance solar cells
Company’s Activities

• Is there any previous experience with collaborative projects?
  • IBS, partner in past and running project:
    • Nano-electronics (ENIAC): PLACES2BE 450 EDL, TAKEMI5,
    • Nano-electronics (ECSEL): TAPES3, OCEAN 12, PINS3
    • Power components: EPPL
    • 4.0 industry: Semi40 (ENIAC)
    • SiC: Challenge (H2020)
    • Diamond: GreenDiamond (H2020)

• What sort of interaction exists with one of the 3 Industry Associations or other ETPs?
  • Member of the board of AENEAS as SME representative
  • Visiting workshops / events
  • Work on SRAs / roadmaps
<table>
<thead>
<tr>
<th><strong>Collaborative project of interest to you</strong></th>
<th><strong>ECSEL, H2020</strong></th>
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<tbody>
<tr>
<td><strong>Scope</strong></td>
<td><strong>Develop new markets</strong></td>
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<tr>
<td><strong>Project idea</strong></td>
<td><strong>Specific ion implantation and related techniques and equipments for SiC component technology</strong></td>
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| **Project impact** | **Develop equipment industry**  
**Strengthen European leadership in SiC** |
| **Project consortium** | **We are searching for partner(s) :**  
**Component design**  
**Substrates and component technology and manufacturing**  
**Application field (ie electrical vehicle)** |
| **Other information** | **optional** |